

# DECLARATION AND POWER OF ATTORNEY FOR ORIGINAL U.S. PATENT APPLICATION

Attorney's Docket No. NSC1P296/P05887

As a below-named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled: **ULTRA-LOW LOOP WIRE BONDING** the specification of which,

- (check one)
1. ☒ is attached hereto.
  2. ☐ was filed on \_\_\_\_\_ as  
U.S. Application No. \_\_\_\_\_  
and was amended on \_\_\_\_\_.
  3. ☐ was filed on \_\_\_\_\_ as  
International PCT Application No. \_\_\_\_\_  
and was amended on \_\_\_\_\_.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, CFR § 1.56.

## Prior Foreign Application(s)

I hereby claim foreign priority benefits under Title 35, United States code, § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or § 365(a) of any PCT International application which designated at least one country other than the United States, listed below and have identified below, by checking the box, any foreign application for patent or inventor's certificate, or PCT International application having a filing date before that of the application on which priority is claimed:

			Priority Benefits Claimed?
			Yes ___ No ___
_____ (Application No.)	_____ (Country)	_____ (Filing Date)	
_____ (Application No.)	_____ (Country)	_____ (Filing Date)	Yes ___ No ___

## Provisional Application(s)

I hereby claim the benefit under 35 U.S.C. §119(e) of any United States provisional application(s) listed below:

_____ (Application No.)	_____ (Filing Date)
_____ (Application No.)	_____ (Filing Date)

**Prior U.S. Application(s)**

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s), or § 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application:

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(Application No.)

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(Filing Date)

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(Status - patented, pending, abandoned)

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(Application No.)

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(Filing Date)

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(Status - patented, pending, abandoned)

**Power of Attorney**

And I hereby appoint the law firm of **Beyer Weaver & Thomas, LLP** and all practitioners who are associated with the Customer Number 022434 as my principal attorneys to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith.

**Direct Correspondence To:****Customer Number: 022434**

22434

**Direct Telephone Calls To:****Phillip P. Lee at telephone number (510) 843-6200**

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Typewritten Full Name of

Sole or First Inventor:

Lim Peng Soon

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Inventor's signature:

Date of Signature:

5 APR 04

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***IN THE UNITED STATES PATENT AND TRADEMARK OFFICE***

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In re application of: Soon et al.

Attorney Docket No.: NSC1P296/P05887

Application No.: NEW

Examiner: UNASSIGNED

Filed: HEREWITH

Group: UNASSIGNED

Title: ULTRA-LOW LOOP WIRE BONDING

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**ASSOCIATE POWER OF ATTORNEY**

Mail Stop Patent Applications  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

The undersigned attorney of record in the subject patent application hereby grants an Associate Power of Attorney to Christopher Byrne, Reg. No. 32,204; John Maxin, Reg. No. 34,668; Peter Y. Wang, Reg. No. 40,452; Andrew S. Viger, Reg. No. 28,552; Eugene C. Conser, Reg. No. 39,149; Coleman F. Reif, Reg. No. 38,593; and Allen R. Tremain, Reg. No. 40,207 all of National Semiconductor Corporation to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.

Please send all correspondence for this application as follows:

**Customer Number**  
**022434**

Please direct any calls to Phillip P. Lee at (510) 843-6200.

Respectfully submitted,  
BEYER WEAVER & THOMAS, LLP



Phillip P. Lee  
Reg. No. 46,866

Date: April 15, 2004